

FAST CORE NO CLEAN CORED WIRE SOLDER

FEATURES

- Enhanced Wetting Properties
- Good for Hard-to-Solder Applications
- Wide Process Window
- Clear, Hard Residues

DESCRIPTION

Fast Core wire solder was designed for applications requiring greater activity than no clean or RMA fluxed solders. Fast Core provides excellent wetting, shiny solder joints and a wide process window on a variety of surface finishes. Fast Core flux promotes good thermal transfer, offering excellent solder penetration into plated through holes or surface mount interconnections. Fast Core wire solder produces low-to-medium, hard, clear post-process residues. Fast Core IPC flux classification is ROM1 and may require removal from sensitive electronics.

STANDARD AVAILABILITY

Fast Core is available in Sn/Pb, Sn/Cu, SAC and SN100C® alloys. Other alloys, diameters and spool sizes may be available upon request.

Diameter	Spool Size
.010	½ lb.
.015	½ lb.
.020	1 lb.
.032	1 lb.
.040	1 lb.
.050	1 lb.
.062	1 lb.



APPLICATION

Best results are obtained with solder iron tip temperature between 300° - 400°C (575° - 750°F) for leaded alloys and 370° - 425°C (700° - 800°F) for lead-free and SN100C® alloys. If additional flux is required AIM NC280 flux is recommended.

HANDLING & STORAGE

Time	Temperature
Indefinite	Proper storage conditions

Store cored wire in a clean, dry area away from moisture and sunlight. Do not freeze this product.


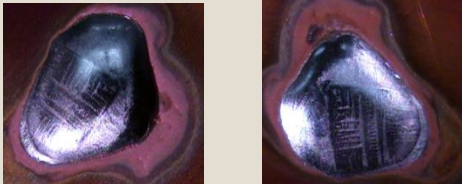

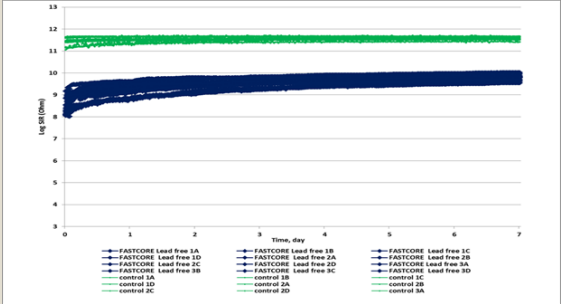
CLEANING

Fast Core can be cleaned with many commercially available flux removers. Contact AIM for specific information.

SAFETY

Use with adequate ventilation and proper personal protective equipment. Refer to the accompanying SDS for any specific emergency information. Do not dispose of any hazardous materials in non-approved containers.

TEST DATA SUMMARY

Name	Test Method	Results	
IPC Flux Classification	J-STD-004	ROM1	
IPC Flux Classification	J-STD-004B 3.3.1	ROM1	
Name	Test Method	Results	Image
Copper Mirror	J-STD-004B 3.4.1.1 IPC-TM-650 2.3.32	LOW	
Corrosion	J-STD-004B 3.4.1.2 IPC-TM-650 2.6.15	PASS	
Quantitative Halides	J-STD-004B 3.4.1.3 IPC-TM-650 2.3.28.1	Br 0.00% Cl: 0.03% Typical	
Qualitative Halides, Silver Chromate	J-STD-004B 3.5.1.1 IPC-TM-650 2.3.33	PASS	
Qualitative Halides, Fluoride Spot	J-STD-004B 3.5.1.2 IPC-TM-650 2.3.35.1	No fluoride	
Surface Insulation Resistance	J-STD-004 3.4.1.4 IPC-TM-650 2.6.3.3	PASS	
Surface Insulation Resistance	J-STD-004B 3.4.1.4 IPC-TM-650 2.6.3.7	All measurements on all test patterns exceed the 100 MΩ	
Acid Value Determination	J-STD-004B 3.4.2.2 IPC-TM-650 2.3.13	224 KOH / g Flux Typical	
Visual	J-STD-004B 3.4.2.5	PASS	
Wetting	J-STD-005A 3.9 IPC-TM-650 2.4.45	PASS	

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